



## Material Content Data Sheet



<b>Sales Product Name</b>		IPP100N10S3-05		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000408226							
<b>Package</b>		PG-TO220-3-1		<b>Weight*</b>		2042.78 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	15.224	0.75	0.75	7453	7453	
leadframe	non noble metal	iron	7439-89-6	1.407	0.07		689		
	inorganic material	phosphorus	7723-14-0	0.422	0.02		207		
	non noble metal	copper	7440-50-8	1404.801	68.77	68.86	687690	688586	
wire	non noble metal	aluminium	7429-90-5	8.862	0.43	0.43	4338	4338	
encapsulation	organic material	carbon black	1333-86-4	8.717	0.43		4267		
	plastics	epoxy resin	-	95.884	4.69		46938		
	inorganic material	silicondioxide	60676-86-0	476.514	23.33	28.45	233267	284472	
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10506	10506	
plating	non noble metal	nickel	7440-02-0	0.244	0.01		119		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	119	
solder	noble metal	silver	7440-22-4	0.231	0.01		113		
	non noble metal	tin	7440-31-5	0.185	0.01		91		
	non noble metal	lead	7439-92-1	8.828	0.43	0.45	4322	4526	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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